3.3 V 2.5 Gb/s Multi Level Clock/Data Input to CML Receiver/ Buffer/ Translator

Description

The NB4N11M is a differential 1-to-2 clock/data distribution/translation chip with CML output structure, targeted for high-speed clock/data applications. The device is functionally equivalent to the EP11, LVEP11, SG11 or 7L11M devices. Device produces two identical differential output copies of clock or data signal operating up to 2.5 GHz or 2.5 Gb/s, respectively. As such, NB4N11M is ideal for SONET, GigE, Fiber Channel, Backplane and other clock/data distribution applications.

Inputs accept LVPECL, CML, LVCMOS, LVTTL, or LVDS (See Table 5). The CML outputs are 16 mA open collector (See Figure 18) which requires resistor (R_L) load path to V_{TT} termination voltage. The open collector CML outputs must be terminated to V_{TT} at power up. Differential outputs produces current–mode logic (CML) compatible levels when receiver loaded with 50 Ω or 25 Ω loads connected to 1.8 V, 2.5 V or 3.3 V supplies (see Figure 19). This simplifies device interface by eliminating a need for coupling capacitors.

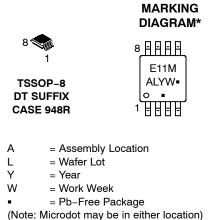
The device is offered in a small 8-pin TSSOP package.

Application notes, models, and support documentation are available at www.onsemi.com.

Features

- Maximum Input Clock Frequency > 2.5 GHz
- Maximum Input Data Rate > 2.5 Gb/s
- Typically 1 ps of RMS Clock Jitter
- Typically 10 ps of Data Dependent Jitter @ 2.5 Gb/s, $R_L = 25 \Omega$
- 420 ps Typical Propagation Delay
- 150 ps Typical Rise and Fall Times
- Operating Range: V_{CC} = 3.0 V to 3.6 V with V_{EE} = 0 V and V_{TT} = 1.8 V to 3.6 V
- Functionally Compatible with Existing 2.5 V / 3.3 V LVEL, LVEP, EP, and SG Devices
- These are Pb-Free Devices*





*For additional marking information, refer to Application Note AND8002/D.

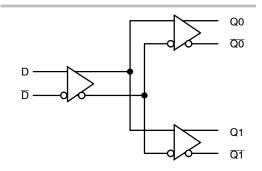
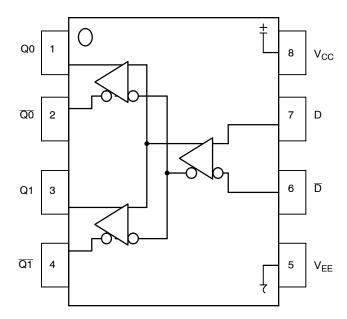


Figure 1. Functional Block Diagram

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.





Pin	Name	I/O	Description
1	Q0	CML Output	Noninverted differential output. Typically receiver terminated with 50 Ω resistor to V _{TT} . Open collector CML outputs must be terminated to V _{TT} at powerup.
2	<u>Q0</u>	CML Output	Inverted differential output. Typically receiver terminated with 50 Ω resistor to V _{TT} . Open collector CML outputs must be terminated to V _{TT} at powerup.
3	Q1	CML Output	Noninverted differential output. Typically receiver terminated with 50 Ω resistor to V_TT. Open collector CML outputs must be terminated to V_TT at powerup.
4	<u>Q1</u>	CML Output	Inverted differential output. Typically receiver terminated with 50 Ω resistor to V _{TT} . Open collector CML outputs must be terminated to V _{TT} at powerup.
5	V _{EE}	-	Negative supply voltage.
6	D	LVPECL, CML, HSTL, LVCMOS, LVDS, LVTTL Input	Inverted differential input.
7	D	LVPECL, CML, HSTL, LVCMOS, LVDS, LVTTL Input	Noninverted differential input.
8	V _{CC}	_	Positive supply voltage.

Table 2. ATTRIBUTES

Characteris	Value				
ESD Protection	Human Body Model Machine Model	> 1000 V > 70 V			
Moisture Sensitivity (Note 1)	Level 1				
Flammability Rating	UL 94 V-0 @ 0.125 in				
Transistor Count	197				
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test					

1. For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply	V _{EE} = -0.5 V		4	V
V_{EE}	Negative Power Supply	V _{CC} = +0.5 V		-4	V
VI	Positive Input Negative Input	V _{EE} = 0 V V _{CC} = 0 V	$\begin{array}{l} V_{I} = V_{CC} + 0.4 \ V \\ V_{I} = V_{EE} - 0.4 \ V \end{array}$	4 4	V V
V _O	Output Voltage Minimum Maximum			V _{EE} + 600 V _{CC} + 400	mV mV
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient) (Note 2)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	1S2P (Note 2)	TSSOP-8	41 to 44	°C/W
T _{sol}	Wave Solder	< 3 Sec @ 260°C		265	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.
JEDEC standard multilayer board – 1S2P (1 signal, 2 power) with 8 filled thermal vias under exposed pad.

Symbol	Characteristic	Min	Тур	Max	Unit
I _{CC}	Power Supply Current (Inputs and Outputs Open)		25	35	mA
R _L = 50	Ω, V _{TT} = 3.6 V to 2.5 V				-
V _{OH}	Output HIGH Voltage (Note 3)	V _{TT} – 60	V _{TT} – 10	V _{TT}	mV
V _{OL}	Output LOW Voltage (Note 3)	V _{TT} – 1100	V _{TT} – 800	V _{TT} – 640	mV
V _{OD}	Differential Output Voltage Magnitude	640	780	1000	mV
R _L = 25	Ω, V _{TT} = 3.6 V to 2.5 V ±5%				
V _{OH}	Output HIGH Voltage (Note 3)	V _{TT} – 60	V _{TT} – 10	V _{TT}	mV
V _{OL}	Output LOW Voltage (Note 3)	V _{TT} – 550	V _{TT} – 400	V _{TT} – 320	mV
V _{OD}	Differential Output Voltage Magnitude	320	390	500	mV
R _L = 50	Ω, V _{TT} = 1.8 V ±5%				
V _{OH}	Output HIGH Voltage (Note 3)	V _{TT} – 170	V _{TT} – 10	V _{TT}	mV
V _{OL}	Output LOW Voltage (Note 3)	V _{TT} – 1100	V _{TT} – 800	V _{TT} – 640	mV
V _{OD}	Differential Output Voltage Magnitude	570	780	1000	mV
R _L = 25	Ω, V _{TT} = 1.8 V \pm 5%				
V _{OH}	Output HIGH Voltage (Note 3)	V _{TT} – 85	V _{TT} – 10	V _{TT}	mV
V _{OL}	Output LOW Voltage (Note 3)	V _{TT} – 500	V _{TT} – 400	V _{TT} – 320	mV
V _{OD}	Differential Output Voltage Magnitude	285	390	500	mV
DIFFER	ENTIAL INPUT DRIVEN SINGLE-ENDED (Figures 14 and 16)				
V _{th}	Input Threshold Reference Voltage Range (Note 5)	V _{EE}		V _{CC}	mV
V _{IH}	Single-ended Input HIGH Voltage	V _{th} + 100		V _{CC} + 400	mV
V_{IL}	Single-ended Input LOW Voltage	V _{EE} – 400		V _{th} – 100	mV
DIFFER	ENTIAL INPUTS DRIVEN DIFFERENTIALLY (Figures 15 and 17)				
V _{IHD}	Differential Input HIGH Voltage	V _{EE}		V _{CC} + 400	mV
V_{ILD}	Differential Input LOW Voltage	V _{EE} – 400		V _{CC} – 100	mV
V_{CMR}	Input Common Mode Range (Differential Configuration)	V _{EE}		V _{CC}	mV
V _{ID}	Differential Input Voltage Magnitude (V _{IHD} - V _{ILD}) (Note 7)	100		$V_{CC} - V_{EE}$	mV
C _{IN}	Input Capacitance (Note 7)		1.5		pF

Table 4. DC CHARACTERISTICS, CLOCK Inputs, CML Outputs V_{CC} = 3.0 V to 3.6 V, V_{FF} = 0 V, T_A = -40°C to +85°C

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. CML outputs require RL receiver termination resistors to VTT for proper operation. Outputs must be connected through RL to VTT at power Unit outputs require no receiver termination resistors to v_{TT} for proper operation. I up. The output parameters vary 1:1 with V_{TT}.
 Input parameters vary 1:1 with V_{CC}.
 V_{th} is applied to the complementary input when operating in single-ended mode.

6. V_{CMR} (MIN) varies 1:1 with V_{EE} , V_{CMR} max varies 1:1 with V_{CC} . 7. Parameter guaranteed by design and evaluation but not tested in production.

	Characteristic		−40°C		25°C		85°C				
Symbol			Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V _{OUTPP}	$\begin{array}{l} \mbox{Output Voltage Amplitude } (R_L = 50 \ \Omega) \\ f_{in} \leq 1 \ GHz \\ (See Figure 12) \\ f_{in} \leq 1.5 \ GHz \\ f_{in} \leq 2.5 GHz \end{array}$	550 400 150	660 640 400		550 400 150	660 640 400		550 400 150	660 640 400		mV
V _{OUTPP}	$\begin{array}{l} \text{Output Voltage Amplitude } (\text{R}_{\text{L}} = 25 \ \Omega) \\ & f_{\text{in}} \leq 1 \ \text{GHz} \\ \text{(See Figure 12)} & f_{\text{in}} \leq 1.5 \ \text{GHz} \\ & f_{\text{in}} \leq 2.5 \text{GHz} \end{array}$	280 280 100	370 360 300		280 280 100	370 360 400		280 280 100	370 360 400		mV
f _{DATA}	Maximum Operating Data Rate		2.5		1.5	2.5		1.5	2.5		Gb/s
t _{PLH} , t _{PHL}	Propagation Delay to Output Differential @ 0.5 GHz	300	420	600	300	420	600	300	420	600	ps
t _{SKEW}	Duty Cycle Skew (Note 9) Within Device Skew Device to Device Skew (Note 13)		2 5 20	20 25 100		2 5 20	20 25 100		2 5 20	20 25 100	ps
UITTER	$\begin{array}{l} \text{RMS Random Clock Jitter } R_L = 50 \ \Omega \text{ and} \\ R_L = 25 \ \Omega \text{ (Note 11)} & f_{in} = 750 \ \text{MHz} \\ f_{in} = 1.5 \ \text{GHz} \\ f_{in} = 2.5 \ \text{GHz} \\ \text{Peak-to-Peak Data Dependent Jitter } R_L = 50 \ \Omega \\ f_{DATA} = 1.5 \ \text{Gb/s} \\ \text{(Note 12)} & f_{DATA} = 2.5 \ \text{Gb/s} \\ \text{Peak-to-Peak Data Dependent Jitter } R_L = 25 \ \Omega \\ f_{DATA} = 1.5 \ \text{Gb/s} \\ \text{(Note 12)} & f_{DATA} = 1.5 \ \text{Gb/s} \\ \text{(Note 12)} & f_{DATA} = 2.5 \ \text{Gb/s} \\ \text{(Note 12)} & f_{DATA} = 2.5 \ \text{Gb/s} \\ \end{array}$		1 1 15 20 5 10	3 3 55 85 35 35		1 1 15 20 5 10	3 3 55 85 35 35		1 1 15 20 5 10	3 3 55 85 35 35	ps
V _{INPP}	Input Voltage Swing/Sensitivity (Differential Configuration) (Note 10)	100			100			100			mV
t _r t _f	Output Rise/Fall Times @ 0.5 GHz Q, Q (20% - 80%)		150	300		150	300		150	300	ps

Table 5. AC CHARACTERISTICS V_{CC} = 3.0 V to 3.6 V, V_{EE} = 0 V; (Note 8)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

8. Measured by forcing V_{INPP} (MIN) from a 50% duty cycle clock source. All output loaded with an external R_L = 50 Ω and R_L = 25 Ω to V_{TT}. Outputs must be connected through R_L to V_{TT} at power up. Input edge rates 150 ps (20% – 80%).
Duty cycle skew is measured between differential outputs using the deviations of the sum of T_{pw-} and T_{pw+} @ 0.5 GHz.
V_{INPP} (MAX) cannot exceed V_{CC} – V_{EE}. Input voltage swing is a single-ended measurement operating in differential mode.

11. Additive RMS jitter with 50% duty cycle clock signal.

12. Additive peak-to-peak data dependent jitter with input NRZ data signal (PRBS 2²³-1).

13. Device to device skew is measured between outputs under identical transition @ 0.5 GHz.

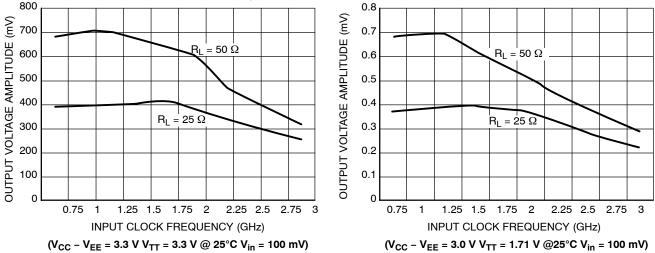
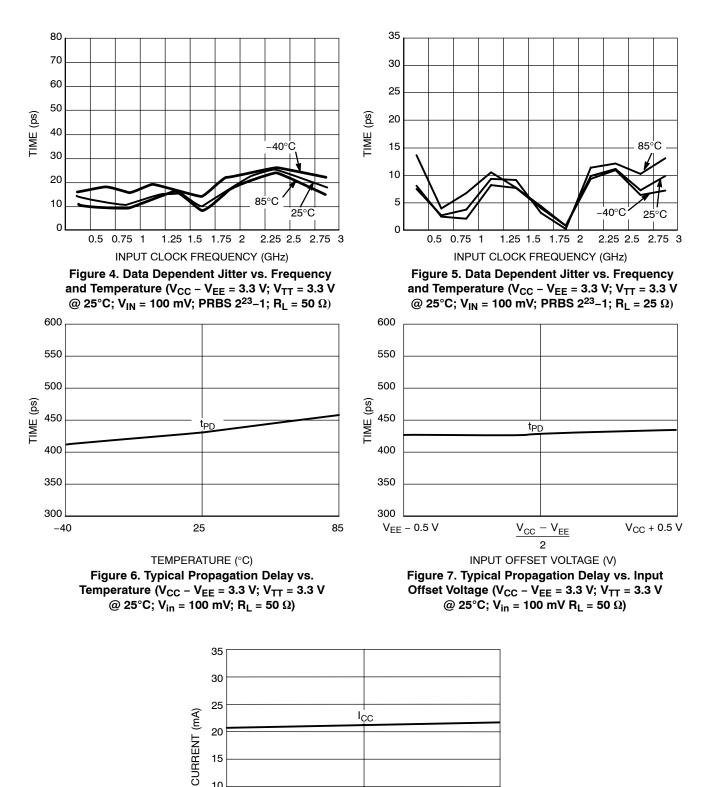


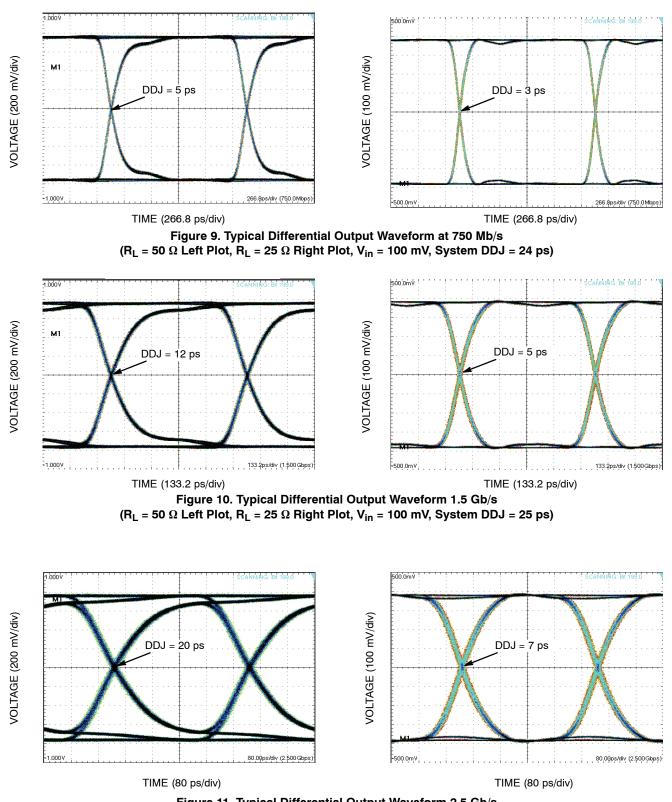
Figure 3. Output Voltage Amplitude (V_{OUTPP}) versus Input Clock Frequency (f_{IN}) at Ambient Temperature (Typical)

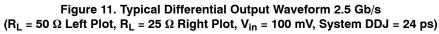
NB4N11M

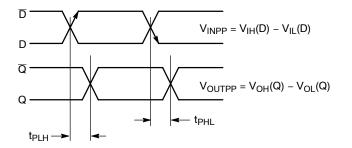


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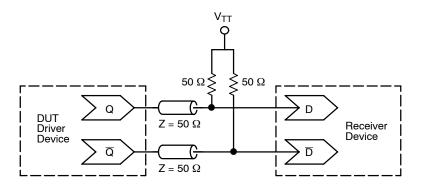
TEMPERATURE (°C) Figure 8. Supply Current vs. Temperature 85













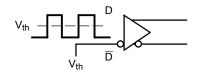


Figure 14. Differential Input Driven Single-Ended

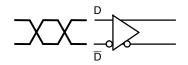
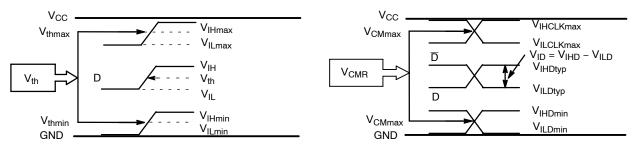
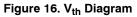
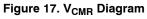


Figure 15. Differential Inputs Driven Differentially







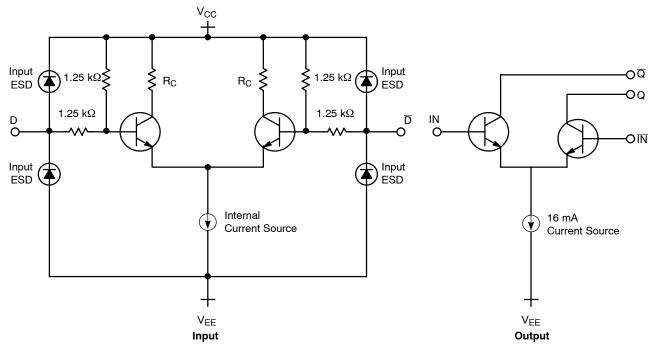


Figure 18. CML Input and Output Structure

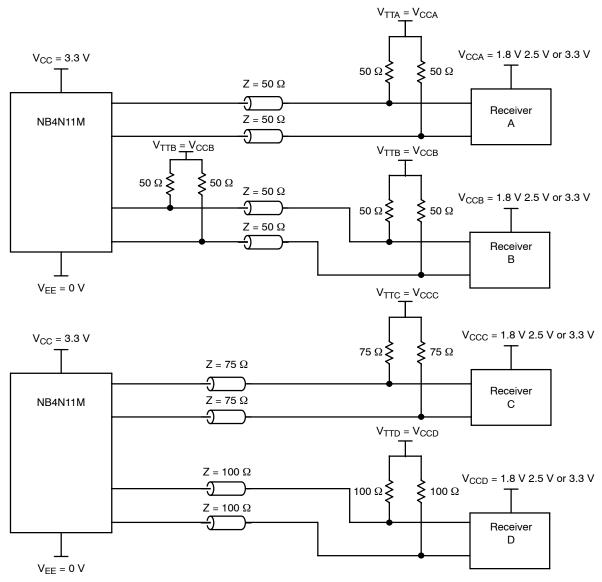


Figure 19. Typical Examples of the Application Interface

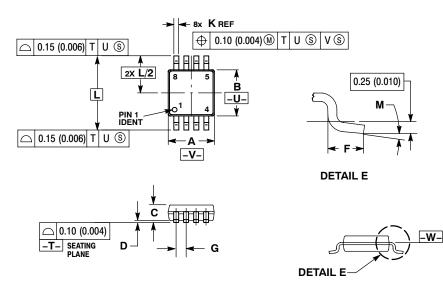
ORDERING INFORMATION

Device	Package	Shipping [†]
NB4N11MDTG	TSSOP-8 (Pb-Free)	100 Units / Rail
NB4N11MDTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

TSSOP-8 DT SUFFIX PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- 2 DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- (0.000) FER SIDE. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) 4. PER SIDE. TERMINAL NUMBERS ARE SHOWN FOR
- 5.
- REFERENCE ONLY. 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-

	MILLIN	IETERS	INCHES					
DIM	DIM MIN MAX		MIN	MAX				
Α	2.90	3.10	0.114	0.122				
В	2.90 3.10		0.114	0.122				
C	0.80 1.10		0.031	0.043				
D	0.05	0.05 0.15		0.006				
F	0.40	0.40 0.70		0.028				
G	0.65	0.65 BSC		BSC				
Κ	0.25	0.40	0.010	0.016				
L	4.90	4.90 BSC		BSC				
M	0°	6 °	0°	6°				

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 8P34\$1102NLGI8
 8T53S111NLGI
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 CDCUA877ZQLT

 CDCE913QPWRQ1
 CDC2516DGGR
 8SLVP2104ANBGI/W
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 LV5609LP-E
 5T9950PFGI
 STCD2400F35F

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